

C-DWG

REV.	ECN NO.	DESCRIPTION	DATE	DESIGN
A	--	INITIAL RELEASED	2019.9.25	HL.W

NOTE:

1.MATERIAL SPECIFICATION:

- 1-1.MOLDING:THERMOPLASTIC,COLOR:BLACK,UL94 V-0.
- 1-2.COVER:THERMOPLASTIC,COLOR:BLACK,UL94 V-0.
- 1-3.MIDDLE:THERMOPLASTIC,COLOR:BLACK,UL94 V-0.
- 1-4.USB3.0 CONTACTS: BRASS.
- 1-5.USB2.0 CONTACTS: PHOSPHOR BRONZE.
- 1-6.FRONT SHELL: STAINLESS STEEL
- 1-7.BACK SHELL: COLD-ROLLED CARBON STEEL.
- 1-8.IRON SHELL: STAINLESS STEEL.

2.PLATING SPECIFICATION:

2-1.USB3.0&USB2.0 CONTACTS:

Ni 50u" MIN. UNDER PLATED OVER ALL.

Gold Flash PLATED ON THE FUNCTIONAL AREA OF CONTACT.

100u" MIN MATTE TIN PLATED ON SOLDER AREA.

2-2.FRONT SHELL:CLEARING ONLY

2-3.BACK SHELL:Ni 50u" MIN. UNDER PLATED OVER ALL.

2-4.IRON SHELL:CLEARING ONLY

3.MECHANICAL PERFORMANCE,

3-1.INSERTION FORCE: 3.5kgf MAX

3-2.REMOVAL FORCE: 1.0kgf MIN

3-3.DURABILITY: 1500 CYCLES.

3-4.OPERATING TEMPERATURE:-25°C~+85°C

4.ELECTRICAL PERFORMANCE,

4-1.INSULATION RESISTANCE: 100M Ω MIN

4-2.DIELECTRIC WITHSTAND VOLTAGE,AC 100V FOR 1 MINUTE.

4-3.CURRENT: 1.8A MAX FOR PIN1 AND PIN4

AND 0.25A FOR ALL THE OTHER PIN

4-4.CONTACT RESISTANCE:30 m Ω MAX INITIAL FOR PIN AND PIN450 m Ω MAX INITIAL FOR ALL OTHER CONTACTS .10m Ω MAX CHANGE AFTER DURABILITY TEST.

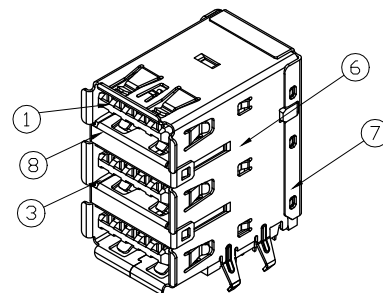
5.HALOGEN FREE COMPLIANT.

6.WAVE SOLDER:

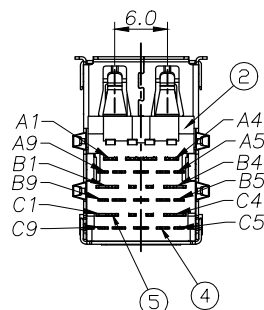
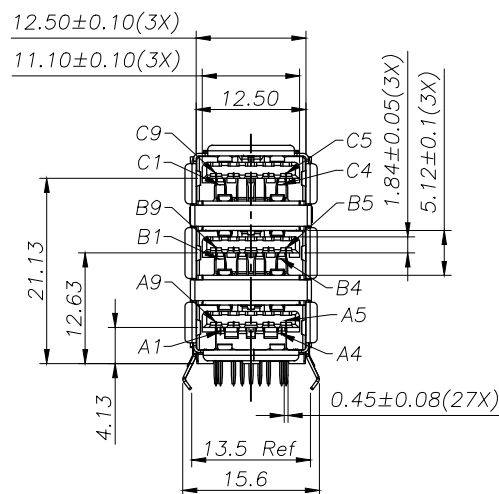
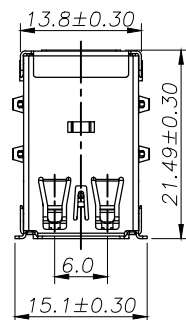
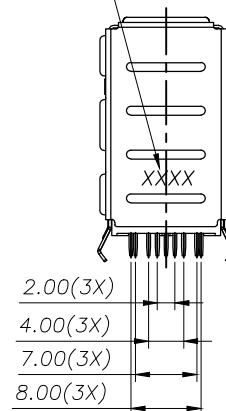
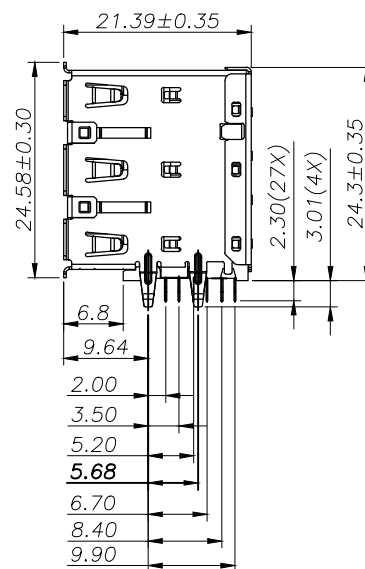
THE CONNECTOR SHALL BE MOUNTED ON THE PCB. THE TEMPERATURE OF THE SOLDER SHALL BE 265 $\pm$ 5 °C AND IMMERSION DURATION 10 SECONDS.

7.DATE CODE: XX XX

WEEK
YEAR



DATE CODE
SEE NOTE 7



PART P/N:
12HU-303B-A841 * T

G: G/F Au

B: 15u" Au

C: 30u" Au

DIM	TOL	DIM	DEG
X	± 0.50	X°	$\pm 8^\circ$
X.X	± 0.35	X.X°	$\pm 5^\circ$
X.XX	± 0.25	X.XX°	$\pm 3^\circ$
X.XXX	± 0.15	X.XXX°	$\pm 2^\circ$
DESIGN:	HL.W	2019.9.25	
CHECK:			
APPROVED			

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FILE:

DRAW NAME:

DRAW NO.

3 PORTS USB3.0 A FEMALE

P/N: 12HU-303B-A841*T

R/A DIP TYPE

UNIT: mm

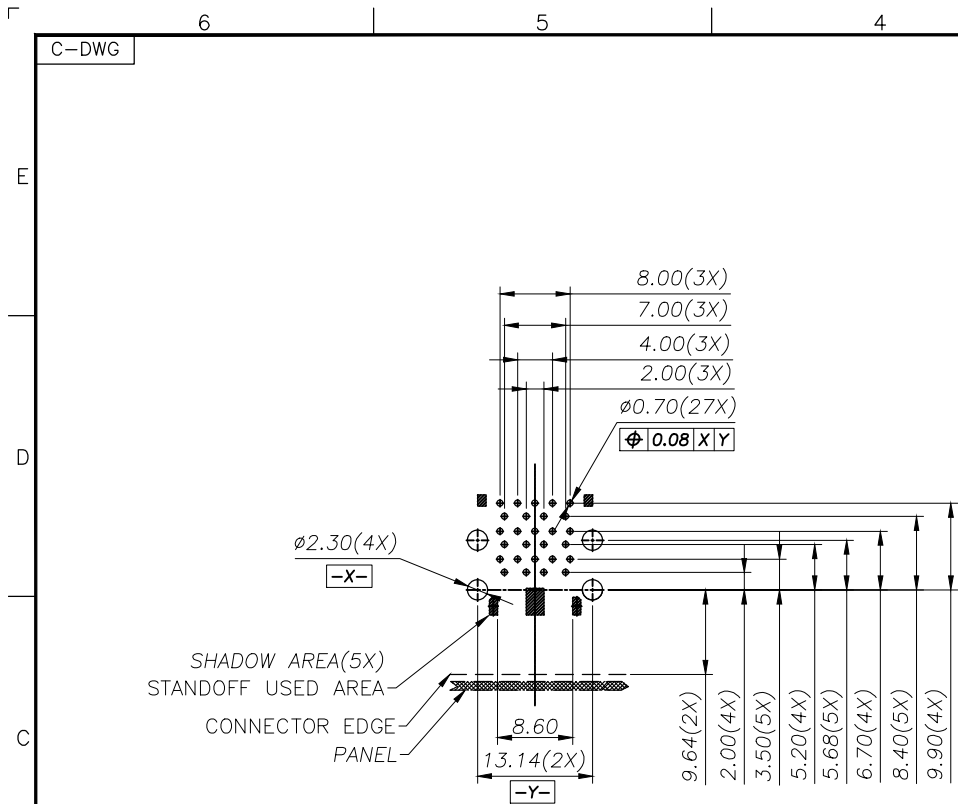
SCALE: 1:1

MODEL:

REV: A

SHEET: 1/3





RECOMMENDED PCB LAYOUT(TOP VIEW)
THICKNESS 1.60±0.10mm; DEFAULT TOLERANCE: ±0.05

PIN ASSIGNMENTS

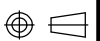
PIN NUMBER	SIGNAL NAME	DESCRIPTION
A1&B1&C1	VBUS	POWER
A2&B2&C2	D-	USB 2.0 DIFFERENTIAL PAIR
A3&B3&C3	D+	
A4&B4&C4	GND	GROUND FOR POWER RETURN
A5&B5&C5	StdA-SSR-	SUPER-SPEED RECEIVER DIFFERENTIAL PAIR
A6&B6&C6	StdA-SSR+	
A7&B7&C7	GND-DRAIN	GROUND FOR SIGNAL RETURN
A8&B8&C8	StdA-SST-	SUPER-SPEED TRANSMITTER DIFFERENTIAL PAIR
A9&B9&C9	StdA-SST+	
SHELL	SHIELD	CONNECTOR METAL SHELL

8	IRON SHELL	1	STAINLESS STEEL	CLEARING ONLY
7	BACK SHELL	1	COLD-ROLLED CARBON STEEL	Ni 50u" MIN. UNDER PLATED OVER ALL.
6	FRONT SHELL	1	STAINLESS STEEL	50u" MIN TIN PLATED ON SOLDER AREA.
5	USB3.0 CONTACTS	15	BRASS	Ni 50u" MIN. UNDER PLATED OVER ALL. Gold PLATED ON THE FUNCTIONAL AREA OF CONTACT. 100u" MIN TIN PLATED ON SOLDER AREA.
4	USB2.0 CONTACTS	12	PHOSPHOR BRONZE	Ni 50u" MIN. UNDER PLATED OVER ALL. Gold PLATED ON THE FUNCTIONAL AREA OF CONTACT. 100u" MIN TIN PLATED ON SOLDER AREA.
3	MIDDLE	2	LCP,UL94 V0	MOLDED COLOR: BLACK.
2	COVER	1	LCP,UL94 V0	MOLDED COLOR: BLACK.
1	MOLDING	3	LCP,UL94 V0	MOLDED COLOR: BLACK.

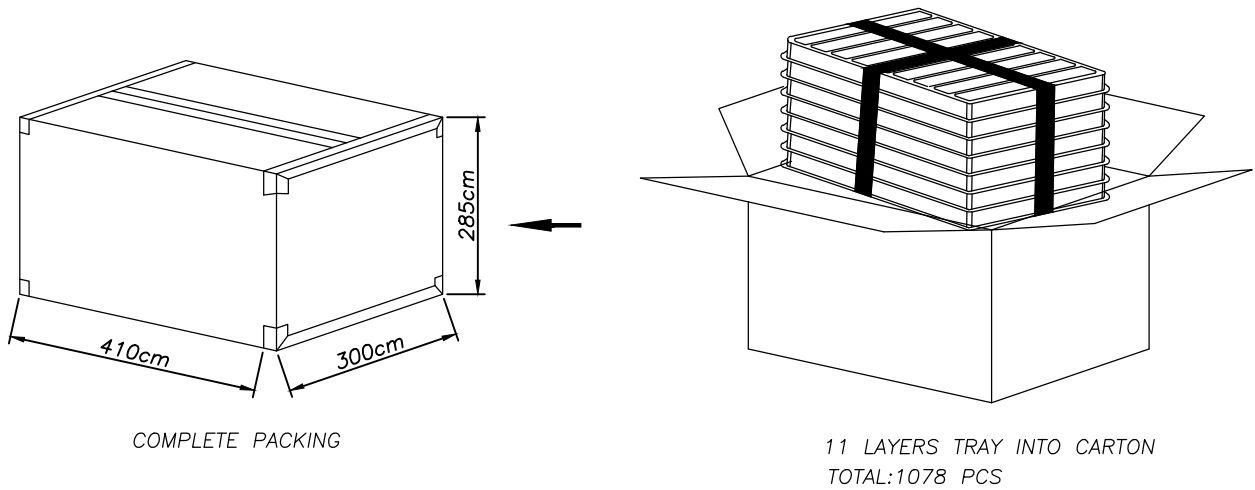
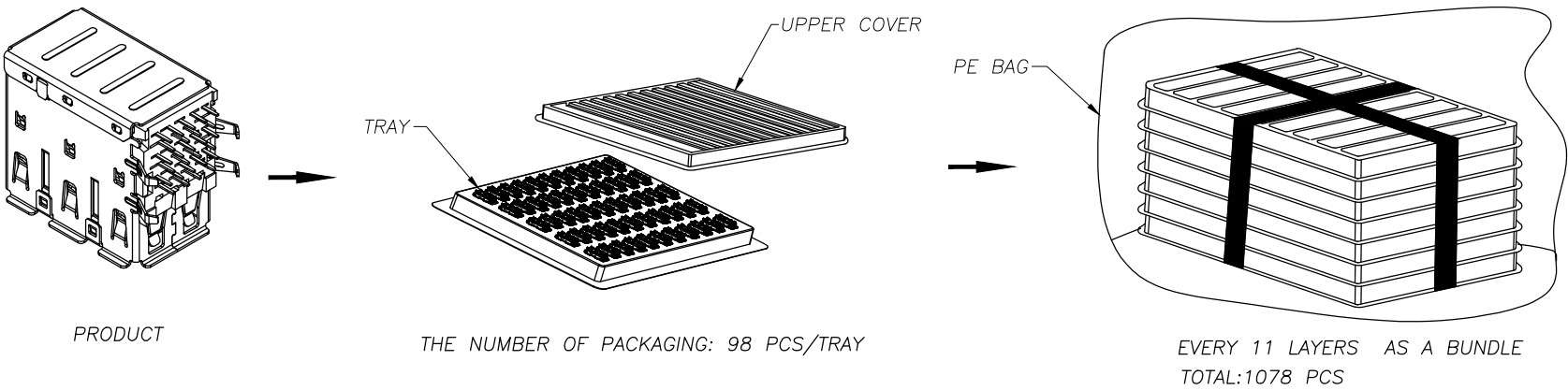
NO.	DESCRIPTION	QTY.	MATERIAL	TREATMENT
DIM	TOL	DIM	DEG	
X	±0.50	X"	±8°	
X.X	±0.35	X.X"	±5°	
X.XX	±0.25	X.XX"	±3°	
X.XXX	±0.15	X.XXX"	±2°	
DESIGN:	HL.W	2019.9.25		
CHECK:				
APPROVED				
FILE:				
DRAW NO.				
P/N: 12HU-303B-A841*T				
UNIT: mm	SCALE: 1:1	MODEL:		
REV: A	SHEET: 2/3			

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DRAW NAME:
3 PORTS USB3.0 A FEMALE
R/A DIP TYPE



REV.	ECN NO.	DESCRIPTION	DATE	DESIGN
A	--	INITIAL RELEASED	2019.9.25	HL.W



THE NUMBER OF PACKAGING

	TRAY	CARTON
PRODUCTS(PCS)	98	1078

DIM	TOL	DIM	DEG	JOINSOO建舜電子	
X	±0.50	X°	±8°		
X.X	±0.35	X.X°	±5°		
X.XX	±0.25	X.XX°	±3°		
X.XXX	±0.15	X.XXX°	±2°		
DESIGN:	HL.W	2019.9.25		FILE:	DRAW NAME:
CHECK:				DRAW NO.	3 PORTS USB3.0 A FEMALE
				P/N: 12HU-303B-A841*T	R/A DIP TYPE
APPROVED				UNIT: mm	SCALE: 1:1
				REV: A	SHEET: 3/3
					MODEL:

